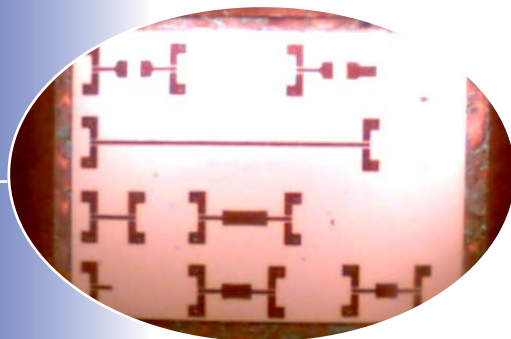
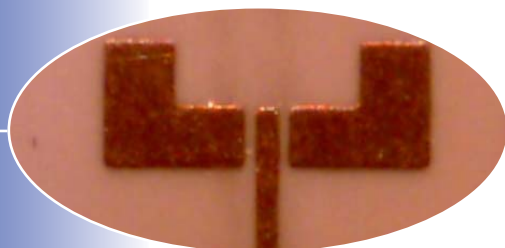


*Electronic Circuits
Fabricated Using LCP
Substrates.*



*Magnified View
of Copper Based
Interconnects Fabricated
on LCP (10X)*



*Magnified View of an
Individual Electronic
Interconnect Pattern
on LCP Material
(60X)*

Overview:

Liquid Crystal Polymer (LCP) is used to fabricate electronic circuitry for a multi-level electronic device.

Process Flow:

1. Start LCP material.
2. Electroless Plating of NiCr base material.
3. Electroplate copper film.
4. Photoresist patterning using the SF-100 and standard positive photoresist material.
5. Wet chemical etch of NiCr/Cu stack.
6. Wet strip photoresist.

